

# 74HC151; 74HCT151

## 8-input multiplexer

Rev. 6 — 28 December 2015

Product data sheet

### 1. General description

The 74HC151; 74HCT151 are 8-bit multiplexer with eight binary inputs (I0 to I7), three select inputs (S0 to S2) and an enable input ( $\bar{E}$ ). One of the eight binary inputs is selected by the select inputs and routed to the complementary outputs (Y and  $\bar{Y}$ ). A HIGH on  $\bar{E}$  forces the output Y LOW and output  $\bar{Y}$  HIGH. Inputs also include clamp diodes that enable the use of current limiting resistors to interface inputs to voltages in excess of  $V_{CC}$ .

### 2. Features and benefits

- Specified in compliance with JEDEC standard no. 7A
- Input levels:
  - ◆ For 74HC151: CMOS level
  - ◆ For 74HCT151: TTL level
- Low-power dissipation
- Non-inverting data path
- ESD protection:
  - ◆ HBM JESD22-A114F exceeds 2 000 V
  - ◆ MM JESD22-A115-A exceeds 200 V
- Multiple package options
- Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$

### 3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74HC151D	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
74HCT151D				
74HC151DB	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SSOP16	plastic shrink small outline package; 16 leads; body width 5.3 mm	SOT338-1
74HCT151DB				
74HC151PW	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1
74HCT151PW				



## 4. Functional diagram

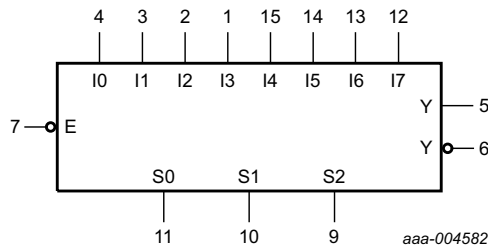


Fig 1. Logic symbol

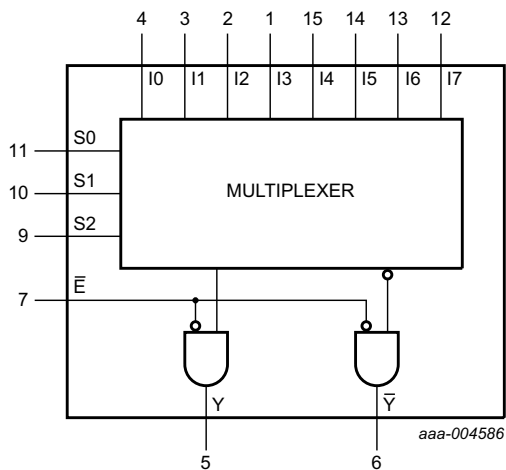


Fig 2. Functional diagram

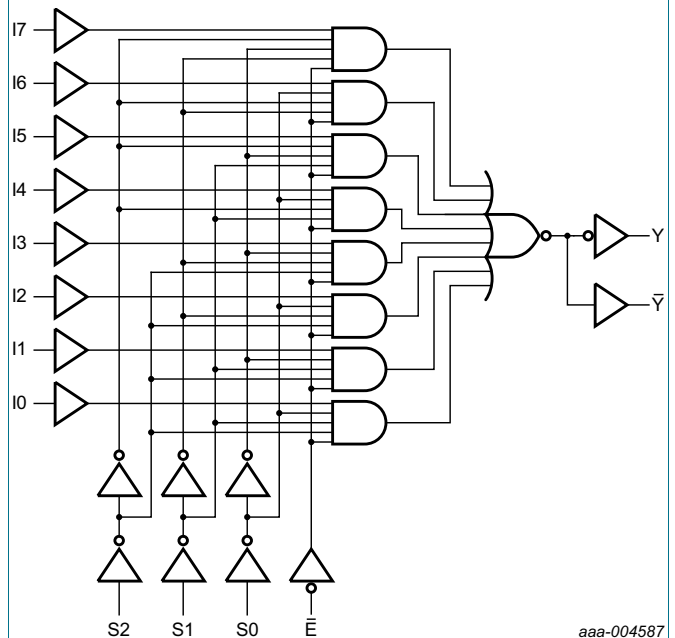


Fig 3. Logic diagram

## 5. Pinning information

### 5.1 Pinning

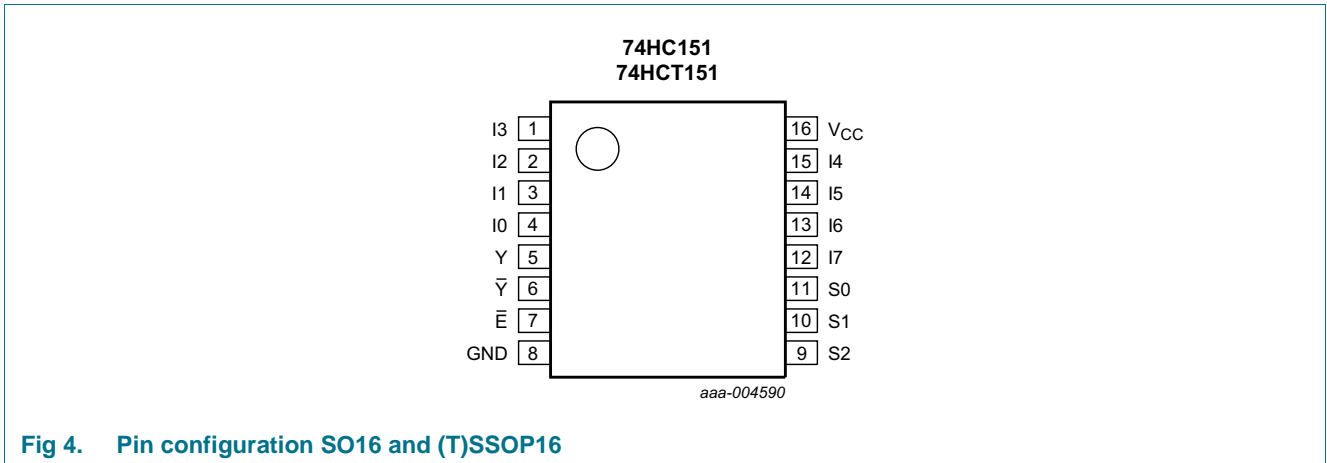


Fig 4. Pin configuration SO16 and (T)SSOP16

### 5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
I0 to I7	4, 3, 2, 1, 15, 14, 13, 12	data inputs
Y	5	multiplexer output
$\bar{Y}$	6	complementary multiplexer output
$\bar{E}$	7	enable input (active LOW)
GND	8	ground (0 V)
S0, S1, S2	11, 10, 9	common data select inputs
VCC	16	supply voltage

## 6. Functional description

Table 3. Function table<sup>[1]</sup>

Input												Output	
$\bar{E}$	S2	S1	S0	I0	I1	I2	I3	I4	I5	I6	I7	$\bar{Y}$	Y
H	X	X	X	X	X	X	X	X	X	X	X	H	L
L	L	L	L	L	X	X	X	X	X	X	X	H	L
L	L	L	L	H	X	X	X	X	X	X	X	L	H
L	L	L	H	X	L	X	X	X	X	X	X	H	L
L	L	L	H	X	H	X	X	X	X	X	X	L	H
L	L	H	L	X	X	L	X	X	X	X	X	H	L
L	L	H	L	X	X	H	X	X	X	X	X	L	H
L	L	H	H	X	X	X	L	X	X	X	X	H	L
L	L	H	H	X	X	X	H	X	X	X	X	L	H
L	H	L	L	X	X	X	X	L	X	X	X	H	L
L	H	L	L	X	X	X	X	H	X	X	X	L	H
L	H	L	H	X	X	X	X	X	L	X	X	H	L
L	H	L	H	X	X	X	X	X	H	X	X	L	H
L	H	H	L	X	X	X	X	X	X	L	X	H	L
L	H	H	L	X	X	X	X	X	X	H	X	L	H
L	H	H	H	X	X	X	X	X	X	X	L	H	L
L	H	H	H	X	X	X	X	X	X	X	H	L	H

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care.

## 7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+7	V
$I_{IK}$	input clamping current	$V_I < -0.5\text{ V}$ or $V_I > V_{CC} + 0.5\text{ V}$	-	$\pm 20$	mA
$I_{OK}$	output clamping current	$V_O < -0.5\text{ V}$ or $V_O > V_{CC} + 0.5\text{ V}$	-	$\pm 20$	mA
$I_O$	output current	$V_O = -0.5\text{ V}$ to $(V_{CC} + 0.5\text{ V})$	-	$\pm 25$	mA
$I_{CC}$	supply current		-	+50	mA
$I_{GND}$	ground current		-50	-	mA
$T_{stg}$	storage temperature		-65	+150	°C

**Table 4. Limiting values ...continued**

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit	
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = -40 °C to +125 °C				
		SO16 package	[1]	-	500	mW
		(T)SSOP16 package	[2]	-	500	mW

[1] For SO16 package: P<sub>tot</sub> derates linearly with 8 mW/K above 70 °C.

[2] For SSOP16 and TSSOP16 packages: P<sub>tot</sub> derates linearly with 5.5 mW/K above 60 °C.

## 8. Recommended operating conditions

**Table 5. Recommended operating conditions**

Voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions	74HC151			74HCT151			Unit
			Min	Typ	Max	Min	Typ	Max	
V <sub>CC</sub>	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
V <sub>I</sub>	input voltage		0	-	V <sub>CC</sub>	0	-	V <sub>CC</sub>	V
V <sub>O</sub>	output voltage		0	-	V <sub>CC</sub>	0	-	V <sub>CC</sub>	V
T <sub>amb</sub>	ambient temperature		-40	+25	+125	-40	+25	+125	°C
Δt/ΔV	input transition rise and fall rate	V <sub>CC</sub> = 2.0 V	-	-	625	-	-	-	ns/V
		V <sub>CC</sub> = 4.5 V	-	1.67	139	-	1.67	139	ns/V
		V <sub>CC</sub> = 6.0 V	-	-	83	-	-	-	ns/V

## 9. Static characteristics

**Table 6. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T <sub>amb</sub> = 25 °C			T <sub>amb</sub> = -40 °C to +85 °C		T <sub>amb</sub> = -40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
<b>74HC151</b>										
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 2.0 V	1.5	1.2	-	1.5	-	1.5	-	V
		V <sub>CC</sub> = 4.5 V	3.15	2.4	-	3.15	-	3.15	-	V
		V <sub>CC</sub> = 6.0 V	4.2	3.2	-	4.2	-	4.2	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 2.0 V	-	0.8	0.5	-	0.5	-	0.5	V
		V <sub>CC</sub> = 4.5 V	-	2.1	1.35	-	1.35	-	1.35	V
		V <sub>CC</sub> = 6.0 V	-	2.8	1.8	-	1.8	-	1.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 6.0 V	5.9	6.0	-	5.9	-	5.9	-	V
		I <sub>O</sub> = -4.0 mA; V <sub>CC</sub> = 4.5 V	3.98	4.32	-	3.84	-	3.7	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 6.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 4.5 V	-	0.15	0.26	-	0.33	-	0.4	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 6.0 V	-	-	±0.1	-	±1.0	-	±1.0	μA
		V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 6.0 V	-	-	8.0	-	80	-	160	μA
C <sub>I</sub>	input capacitance		-	3.5	-	-	-	-	-	pF

**Table 6. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T <sub>amb</sub> = 25 °C			T <sub>amb</sub> = -40 °C to +85 °C		T <sub>amb</sub> = -40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
<b>74HCT151</b>										
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	2.0	1.6	-	2.0	-	2.0	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	-	1.2	0.8	-	0.8	-	0.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = -20 μA	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -4 mA	3.98	4.32	-	3.84	-	3.7	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = 20 μA	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 4.0 mA	-	0.15	0.26	-	0.33	-	0.4	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 5.5 V	-	-	±0.1	-	±1.0	-	±1.0	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 5.5 V	-	-	8.0	-	80	-	160	μA
ΔI <sub>CC</sub>	additional supply current	V <sub>I</sub> = V <sub>CC</sub> - 2.1 V; other inputs at V <sub>CC</sub> or GND; V <sub>CC</sub> = 4.5 V to 5.5 V; I <sub>O</sub> = 0 A								
		per input pin; I <sub>n</sub> inputs	-	45	162	-	203	-	221	μA
		per input pin; $\bar{E}$ input	-	30	108	-	135	-	147	μA
		per input pin; S <sub>n</sub> input	-	150	540	-	675	-	735	μA
C <sub>I</sub>	input capacitance		-	3.5	-	-	-	-	-	pF

## 10. Dynamic characteristics

**Table 7. Dynamic characteristics**

Voltages are referenced to GND (ground = 0 V);  $C_L = 50$  pF unless otherwise specified; for test circuit see [Figure 7](#).

Symbol	Parameter	Conditions	$T_{amb} = 25\text{ °C}$			$T_{amb} = -40\text{ °C}$ to $+85\text{ °C}$		$T_{amb} = -40\text{ °C}$ to $+125\text{ °C}$		Unit
			Min	Typ	Max	Min	Max	Min	Max	
<b>74HC151</b>										
$t_{pd}$	propagation delay	In to Y; see <a href="#">Figure 5</a> [1]								
		$V_{CC} = 2.0\text{ V}$	-	52	170	-	215	-	255	ns
		$V_{CC} = 4.5\text{ V}$	-	19	34	-	43	-	51	ns
		$V_{CC} = 5\text{ V}; C_L = 15\text{ pF}$	-	17	-	-	-	-	-	ns
		$V_{CC} = 6.0\text{ V}$	-	15	29	-	37	-	43	ns
		In to $\bar{Y}$ ; see <a href="#">Figure 5</a> [1]								
		$V_{CC} = 2.0\text{ V}$	-	58	185	-	230	-	280	ns
		$V_{CC} = 4.5\text{ V}$	-	21	37	-	46	-	56	ns
		$V_{CC} = 5\text{ V}; C_L = 15\text{ pF}$	-	17	-	-	-	-	-	ns
		$V_{CC} = 6.0\text{ V}$	-	17	31	-	39	-	48	ns
		Sn to Y; see <a href="#">Figure 6</a> [1]								
		$V_{CC} = 2.0\text{ V}$	-	61	185	-	230	-	280	ns
		$V_{CC} = 4.5\text{ V}$	-	22	37	-	46	-	56	ns
		$V_{CC} = 5\text{ V}; C_L = 15\text{ pF}$	-	19	-	-	-	-	-	ns
		$V_{CC} = 6.0\text{ V}$	-	18	31	-	39	-	48	ns
		Sn to $\bar{Y}$ ; see <a href="#">Figure 6</a> [1]								
		$V_{CC} = 2.0\text{ V}$	-	61	205	-	255	-	310	ns
		$V_{CC} = 4.5\text{ V}$	-	22	41	-	51	-	62	ns
		$V_{CC} = 5\text{ V}; C_L = 15\text{ pF}$	-	19	-	-	-	-	-	ns
		$V_{CC} = 6.0\text{ V}$	-	18	35	-	43	-	53	ns
		$\bar{E}$ to Y; see <a href="#">Figure 6</a>								
		$V_{CC} = 2.0\text{ V}$	-	41	125	-	155	-	190	ns
		$V_{CC} = 4.5\text{ V}$	-	15	25	-	31	-	38	ns
		$V_{CC} = 5\text{ V}; C_L = 15\text{ pF}$	-	12	-	-	-	-	-	ns
$V_{CC} = 6.0\text{ V}$	-	12	21	-	26	-	32	ns		
$\bar{E}$ to $\bar{Y}$ ; see <a href="#">Figure 6</a>										
$V_{CC} = 2.0\text{ V}$	-	47	145	-	180	-	220	ns		
$V_{CC} = 4.5\text{ V}$	-	17	29	-	36	-	44	ns		
$V_{CC} = 5\text{ V}; C_L = 15\text{ pF}$	-	14	-	-	-	-	-	ns		
$V_{CC} = 6.0\text{ V}$	-	14	25	-	31	-	38	ns		
$t_t$	transition time	Y, $\bar{Y}$ ; see <a href="#">Figure 5</a> [2]								
		$V_{CC} = 2.0\text{ V}$	-	19	75	-	95	-	110	ns
		$V_{CC} = 4.5\text{ V}$	-	7	15	-	19	-	22	ns
		$V_{CC} = 6.0\text{ V}$	-	6	13	-	16	-	19	ns



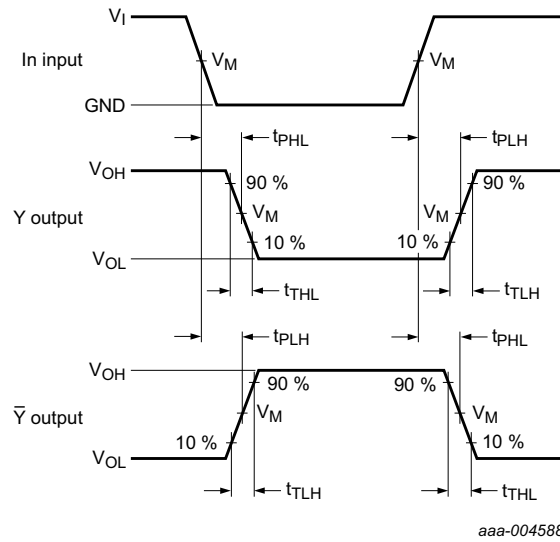
**Table 7. Dynamic characteristics ...continued**

Voltages are referenced to GND (ground = 0 V);  $C_L = 50$  pF unless otherwise specified; for test circuit see [Figure 7](#).

Symbol	Parameter	Conditions	$T_{amb} = 25\text{ °C}$			$T_{amb} = -40\text{ °C to }+85\text{ °C}$		$T_{amb} = -40\text{ °C to }+125\text{ °C}$		Unit	
			Min	Typ	Max	Min	Max	Min	Max		
$C_{PD}$	power dissipation capacitance	$C_L = 50$ pF; $f = 1$ MHz; $V_I = \text{GND to } V_{CC}$	[3]	-	40	-	-	-	-	pF	
<b>74HCT151</b>											
$t_{pd}$	propagation delay	In to Y; see <a href="#">Figure 5</a>	[1]								
		$V_{CC} = 4.5$ V		-	22	38	-	48	-	57	ns
		$V_{CC} = 5$ V; $C_L = 15$ pF		-	19	-	-	-	-	-	ns
		In to $\bar{Y}$ ; see <a href="#">Figure 5</a>	[1]								
		$V_{CC} = 4.5$ V		-	22	38	-	48	-	57	ns
		$V_{CC} = 5$ V; $C_L = 15$ pF		-	19	-	-	-	-	-	ns
		Sn to Y; see <a href="#">Figure 6</a>	[1]								
		$V_{CC} = 4.5$ V		-	23	41	-	51	-	62	ns
		$V_{CC} = 5$ V; $C_L = 15$ pF		-	20	-	-	-	-	-	ns
		Sn to $\bar{Y}$ ; see <a href="#">Figure 6</a>	[1]								
		$V_{CC} = 4.5$ V		-	25	43	-	54	-	65	ns
		$V_{CC} = 5$ V; $C_L = 15$ pF		-	20	-	-	-	-	-	ns
		$\bar{E}$ to Y; see <a href="#">Figure 6</a>	[1]								
		$V_{CC} = 4.5$ V		-	16	29	-	36	-	44	ns
$V_{CC} = 5$ V; $C_L = 15$ pF		-	13	-	-	-	-	-	ns		
$t_t$	transition time	Y, $\bar{Y}$ ; see <a href="#">Figure 5</a>	[2]								
		$V_{CC} = 4.5$ V		-	7	15	-	19	-	22	ns
$C_{PD}$	power dissipation capacitance	$C_L = 50$ pF; $f = 1$ MHz; $V_I = \text{GND to } V_{CC} - 1.5$ V	[3]	-	40	-	-	-	-	pF	

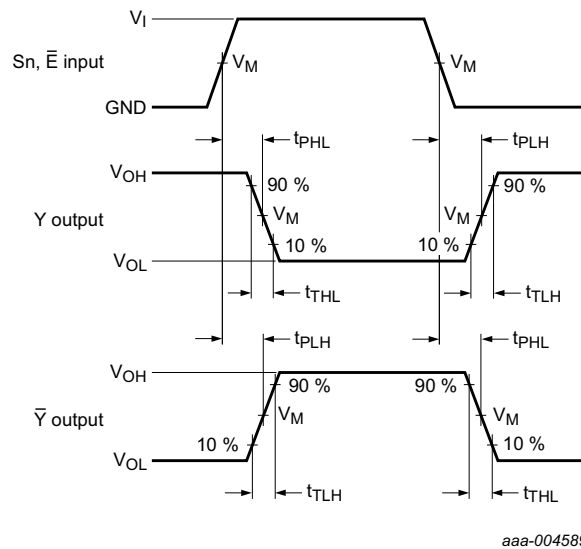
- [1]  $t_{pd}$  is the same as  $t_{PLH}$  and  $t_{PHL}$ .
- [2]  $t_t$  is the same as  $t_{THL}$  and  $t_{TLH}$ .
- [3]  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu\text{W}$ ).  
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o)$  where:  
 $f_i$  = input frequency in MHz;  
 $f_o$  = output frequency in MHz;  
 $C_L$  = output load capacitance in pF;  
 $V_{CC}$  = supply voltage in V;  
 $N$  = number of inputs switching;  
 $\sum(C_L \times V_{CC}^2 \times f_o)$  = sum of outputs.

11. Waveforms



Measurement points are given in [Table 8](#).  
 $V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig 5. Propagation delay input (In) to output (Y,  $\bar{Y}$ ) and the output (Y,  $\bar{Y}$ ) transition time**

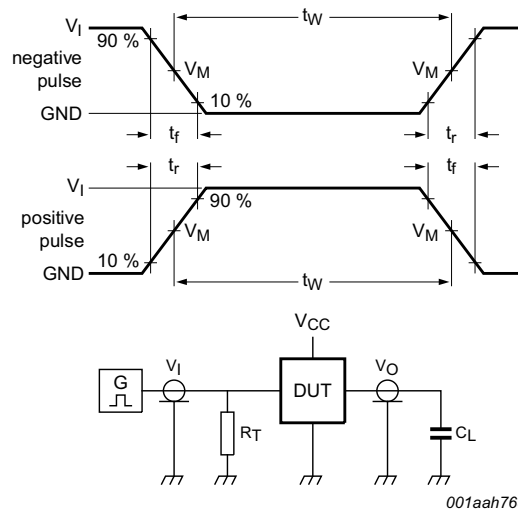


Measurement points are given in [Table 8](#).  
 $V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig 6. Propagation delay input (Sn,  $\bar{E}$ ) to output (Y,  $\bar{Y}$ ) and output (Y,  $\bar{Y}$ ) transitions time**

**Table 8. Measurement points**

Type	Input	Output
	$V_M$	$V_M$
74HC151	$0.5V_{CC}$	$0.5V_{CC}$
74HCT151	1.3 V	1.3 V



001aah768

Test data is given in [Table 9](#).

Definitions test circuit:

$R_T$  = Termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.

$C_L$  = Load capacitance including jig and probe capacitance.

$R_L$  = Load resistance.

S1 = Test selection switch.

**Fig 7. Test circuit for measuring switching times**

**Table 9. Test data**

Type	Input		Load	Test
	$V_I$	$t_r, t_f$	$C_L$	
74HC151	$V_{CC}$	6.0 ns	15 pF, 50 pF	$t_{PLH}, t_{PHL}$
74HCT151	3.0 V	6.0 ns	15 pF, 50 pF	$t_{PLH}, t_{PHL}$

12. Package outline

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1



Fig 8. Package outline SOT109-1 (SO16)

SSOP16: plastic shrink small outline package; 16 leads; body width 5.3 mm

SOT338-1



Fig 9. Package outline SOT338-1 (SSOP16)

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

SOT403-1



Fig 10. Package outline SOT403-1 (TSSOP16)

## 13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

## 14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT151 v.6	20151228	Product data sheet	-	74HC_HCT151 v.5
Modifications:	<ul style="list-style-type: none"> <li>Type numbers 74HC151N and 74HCT151N (SOT38-4) removed.</li> </ul>			
74HC_HCT151 v.5	20150126	Product data sheet	-	74HC_HCT151 v.4
Modifications:	<ul style="list-style-type: none"> <li><a href="#">Table 7</a>: Power dissipation capacitance condition for 74HCT151 is corrected.</li> </ul>			
74HC_HCT151 v.4	20130211	Product data sheet	-	74HC_HCT151 v.3
Modifications:	<ul style="list-style-type: none"> <li>New descriptive title (errata).</li> </ul>			
74HC_HCT151 v.3	20120919	Product data sheet	-	74HC_HCT151_CNV v.2
74HC_HCT151_CNV v.2	19970827	Product specification	-	

## 15. Legal information

### 15.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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[2] The term 'short data sheet' is explained in section "Definitions".

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